ABSOLUTION CONNECTING ELECTRONICS INDUSTRIES® INCOMPLETING	IPC, Bannock	burn, Illinois. A	ll rights reserved un ntions.	nder both	This docume level parts, t	ent is a declar he declaratio	ration of the s	substances es all lowe	within the man r level material	ufacturer listed s for which the	l item. N manufa	Note: if the acturer has	e item is an ass s engineering re	embly with lower esponsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Information															
Company name*	Company uni	Company unique ID			Unique ID Authority					Response Date*					
onsemi												2025-05-13			
Contact Name	Title - Contac	Title - Contact			Phone - Contact*				Email	Email - Contact*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Repres	Title - Representative			Phone - Representative*				Email	Email - Representative*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iter	n Number	Mfr Item Name			Effective Date Version Manufacturing Site		Site	Weigh	nt*	UOM	Unit Type			
	MC74H G	IC4060ADTR2	LOG CMOS COUNTER 14STAGE		AGE	2025-05-13		1	PH1		45.4		mg	Each	
Manufacturing Proccess Informa	tion							·							
Terminal Plating / Grid Array M	aterial	Terminal Base A	Alloy J	-STD-020 MS	TD-020 MSL Rating		Peak Process Body Temper		ture Max Time at Peak Tem		mperature Number of Reflow Cycles		es		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1				260		C	30 seco		econds 3				
Comments															
evel 1 - maximum time at peak temperat	ure during s	oldering is 10-3	0 seconds												
For more information regarding material	composition	n please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach	1.32	mg	Supplier	Silver (Ag)	7440-22-4		0.99	mg
			Supplier	Epoxy resins	129915-35-1		0.33	mg
Lead Frame	20.76	mg	Supplier	Zinc (Zn)	7440-66-6		0.0249	mg
			Supplier	Iron (Fe)	7439-89-6		0.4879	mg
			Supplier	Copper (Cu)	7440-50-8		20.241	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0062	mg
Mold Compound-Black	19.0	mg		Epoxy resin	proprietary data		0.95	mg
			Supplier	Phenolic Resin	Proprietary Data		0.95	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.38	mg
			Supplier	Carbon Black (C)	1333-86-4		0.095	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		16.625	mg
Plating	2.12	mg	Supplier	Palladium (Pd)	7440-05-3		0.1611	mg
			В	Nickel (Ni)	7440-02-0		1.9292	mg
			Supplier	Gold (Au)	7440-57-5		0.0297	mg
Vire Bond - Cu	0.2	mg	Supplier	Copper (Cu)	7440-50-8		0.2	mg